

Filename: PMP5800_REVA_bom.xls

Date: 04/27/2011

PMP5800_REVA BOM

COUNT	RefDes	Value	Description
2	C100, C101 C13, C14, C15,	1500pF	Capacitor, Ceramic, vvV, [temp], [tol]
4	C16 C17, C27, C28, C31, C32, C33, C34, C35, C36, C37, C38, C39, C40, C41, C42, C43, C44, C45, C47, C48, C49, C50, C51, C52, C53, C54, C55, C56, C57, C58, C59, C60, C61,	330uF	Capacitor, 2.5VDC Max, ±20%
36	C64, C69, C70 C18, C19, C20,	10uF	Capacitor, Ceramic, 6.3V, X7R, 15%
4	C21	33pF	Capacitor, Ceramic, 25V, C0G, 5%
2	C2, C4	0.018uF	Capacitor, Ceramic, 50V, X7R, 15%
1	C26	3300pF	Capacitor, Ceramic, 25V, X7R, 15%
2	C30, C66	0.01uF	Capacitor, Ceramic, 25V, X5R, 15%
2	C46, C62 C5, C12, C22, C29, C63, C65, C71,	Open	Capacitor, 2.5VDC Max, ±20%
8	C73	1uF	Capacitor, Ceramic, 16V, X7R, 15%
1	C6	0.22uF	Capacitor, Ceramic, 25V, X7R, 15%
2	C67, C68	0.1uF	Capacitor, Ceramic, 16V, X7R, 15%
1	C7	33pF	Capacitor, Ceramic, 50V, X7R, 15%
2	C72, C74 C8, C9, C10, C23,	1000pF	Capacitor, Ceramic, 50V, X7R, 15%
6	C24, C25	22uF	Capacitor, Ceramic, 25V, X5R, 15%
2	D1, D2	MBR0530	Diode, Schottky, 0.5A, 30V, SOD-123
1	D20	BAT54	Diode, Schottky, 200-mA, 30-V
3	D3, D4, D7 D5, D9, D10, D11, D12, D13, D14, D15, D16, D17,	GREEN	Diode, LED, Green Clear, 20mcd
12	D18, D19	RED	Diode, LED, Red Clear, 20mcd
2	D6, D8	AMBER	Diode, LED, Amber Clear, 6mcd
1	J1	D120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm
1	J18	PTC36SAAN	Header, Male 3-pin, 100mil spacing, (36-pin strip)
2	J2, J3 J4, J9, J10, J11, J12, J13, J14, J15,	ED1981	Terminal Block, 2-pin, 32-A, 9.5mm
11	J16, J17, J19	PTC36SAAN	Header, Male 2-pin, 100mil spacing, (36-pin strip)
1	J5	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm
3	J6, J7, J8	PTC36DAAN	Header, Male 2x4-pin, 100mil spacing (36-pin strip)

2	L1, L2	0.47uH	Inductor, SMT, 30A, 1.53milliohm
2	Q1, Q8	CSD16322Q5	MOSFET, NChan, 25V, 24A, 3.1milliOhm
3	Q12, Q13, Q14 Q15, Q16, Q17, Q18	BSS123	MOSFET, Nch, 100V, 0.17A, 6 Ohm
4	Q3, Q6	BSC020N03M	MOSFET, NChan, 25V, 37A, 1.3milliOhm
2	Q9, Q10, Q11	CSD16321Q5	MOSFET, NChan, 25V, 37A, 1.3milliOhm
3	R1, R8	BSS83P	MOSFET, Pch, -60V, -0.33A, 2 Ohm
2	R100, R101	24.9K	Resistor, Chip, 1/16W, 1%
1	R15	1	Resistor, Chip, 1/2W, 1%
2	R17, R19	7.5k	Resistor, Chip, 1/16W, 1%
2	R18, R20	5.6	Resistor, Chip, 1/16W, 1%
4	R2, R7, R9, R14	short	Resistor, Metal Strip, 1 W, 1%
2	R21, R22	470	Resistor, Chip, 1/16W, 1%
1	R23	10	Resistor, Chip, 1/16W, 1%
1	R24	2.00K	Resistor, Chip, 1/16W, 1%
	R25, R35, R36, R37, R38, R39, R40, R41, R42, R43, R44, R45,	8.87k	Resistor, Chip, 1/16W, 1%
15	R46, R47, R67	10.0K	Resistor, Chip, 1/16W, 1%
1	R26	1	Resistor, Chip, 1/10W, 1%
1	R27	174K	Resistor, Chip, 1/16W, 1%
2	R28, R70	100K	Resistor, Chip, 1/16W, 1%
	R29, R30, R31, R32, R33, R34	180	Resistor, Chip, 1/16W, 1%
2	R4, R10	165K	Resistor, Chip, 1/16W, 1%
	R48, R49, R50, R51, R52, R53,		
7	R54	330	Resistor, Chip, 1/16W, 1%
2	R5, R12	43.2K	Resistor, Chip, 1/16W, 1%
1	R55	90.9K	Resistor, Chip, 1/16W, 1%
1	R56	88.7K	Resistor, Chip, 1/16W, 1%
	R57, R58, R59, R60, R61, R62,		
8	R63, R64	0.05	Resistor, Chip, 1W, 5%
1	R65	10.0K	Resistor, Chip Array, 100 mW ± 0.1%
1	R66	8.06K	Resistor, Chip, 1/16W, 1%
1	R68	0.005	Resistor, Chip, 1W, 5%
1	R69	330	Resistor, Chip Array, 100 mW ± 0.1%
	R71, R72, R73, R74	10	Resistor, Chip, 1/16W, 1%
2	RT1, RT2	150K	NTC Thermistor, 150K Ohms, 1%, 0603
1	RT3	150K	NTC Thermistor, No Stuff, 0603
1	S1	EG1218A	Switch, SPDT, Slide, PC-mount,
1	S2	76SB04	Switch, 4-pole DIP, Raised Rocker
5	SH1, SH2, SH3, SH6, SH7		Short jumper

	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP11, TP12, TP14, TP15, TP17, TP18, TP19, TP20, TP21, TP22, TP23, TP24, TP25, TP26, TP28, TP29, TP31, TP32,		
29	TP33, TP35 TP10, TP13, TP16,	5000	Test Point, Red, Thru Hole Color Keyed
4	TP30	5001	Test Point, Black, Thru Hole Color Keyed
1	TP27	131-4244-00	Adaptor, 3.5-mm probe clip (or 131-5031-00)
1	U1	TPS51621RHA	IC, 2-Phase IMVP-6.5Vcore Controller w/Integrated Drives
1	U2	TPS715A01DRB	IC, High Input Voltage, Micropower, 3.2 μ A @ 80 mA LDO, xx\
1	U3	CD74HCT08D	IC, Quadruple 2-Input Positive-And gates
2	U4, U5	UCC27324D	IC, Dual 4-A High Speed Low-Side Power MOSFET Drivers
1	U6	TLC555CD	IC, Timer, Low-Power CMOS
1	--		PCB

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

Size	Part Number	MFR
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0805 GRM40yyyxxxKvv muRata

D2T 2R5TPL330MFU Sanyo

0805 Std TDK

0402 Std Std

0603 Std Std

0402 Std Std

0402 Std Std

D2T 2R5TPL330MFU Sanyo

0603 Std Std

0603 Std Std

0402 Std Std

0603 Std Std

0603 Std Std

1210 Std Std

SOD-123 MBR0530 On Semi

SOT23 BAT54-V-GS08 Vishay-Liteon

0.079 X 0.049 LTST-C170CKT Lite On

0.079 X 0.049 LTST-C170CKT Lite On

0.079 X 0.049 LTST-C170AKT Lite On

0.40 x 0.35 incl D120/2DS OST

0.100 inch x 3 PTC36SAAN Sullins

0.75 x 0.49 incl ED1981 OST

0.100 inch x 2 PEC02SAAN Sullins

0.27 x 0.25 incl ED1514 OST

0.20 x 0.40 inc PTC36DAAN Sullins

0.400 x 0.453 ir IHLP4040DZERR4 Vishay
QFN5X6mm CSD16413Q5A-R Ciclon
SOT23 BSS123 Fairchild

QFN5X6mm CSD16401Q5A-R Ciclon
QFN5X6mm CSD16401Q5A-R Ciclon
SOT23 BSS83P Infineon
0402 Std Std
2010 STD Vishay
0603 Std Std
0603 Std Std
2512 WSL-2512 xxxx 1% Vishay Dale
0402 Std Std
0402 Std Std
0402 Std Std
0402 Std Std

0402 Std Std
0805 Std Std
0402 Std Std
0402 Std Std

0402 Std Std
0402 Std Std

0402 Std Std
0402 Std Std
0402 Std Std
0402 Std Std

2512 STD STD
1210 ACAC0612441x90(Vishay
0402 Std Std
2512 STD STD
1210 ACAC0612441x90(Vishay

0603 Std Std
0603 Std Std
0603 Std Std
0.457 x 0.157 ir EG1218A E_Switch
0.38 x 0.40 incl 76SB04 Grayhill

0.100 x 0.100 ir 5000 Keystone

0.100 x 0.100 ir 5001 Keystone

0.200 inch 131-4244-00 Tektronix

QFN-40 TPS51621RHA TI

QFN-8 TPS715A01DRBR TI

SO14 SN74HC08D TI

SO-8 UCC3732xD TI

SO8 TLC555D TI

HPA-470 Any

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